



Material Content Data Sheet



Sales Product Name		ESD3V3U4ULC E6327		Issued		20. July 2018		
MA#		MA000892478						
Package		PG-TSLP-9-1		Weight*		1.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.09		898	
	noble metal	gold	7440-57-5	0.005	0.35		3484	
	inorganic material	silicon	7440-21-3	0.040	2.58	3.02	25812	30194
leadframe	non noble metal	nickel	7440-02-0	0.330	21.27	21.27	212747	212747
wire	non noble metal	copper	7440-50-8	0.012	0.80	0.80	8016	8016
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.001	0.03		348	
	organic material	carbon black	1333-86-4	0.011	0.70		6951	
	plastics	epoxy resin	-	0.146	9.38		93844	
	inorganic material	silicondioxide	60676-86-0	0.922	59.41	69.52	594001	695144
leadfinish	noble metal	gold	7440-57-5	0.032	2.05	2.05	20471	20471
plating	noble metal	silver	7440-22-4	0.052	3.34	3.34	33428	33428
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com